eMemory

A Leading Logic NVM Company

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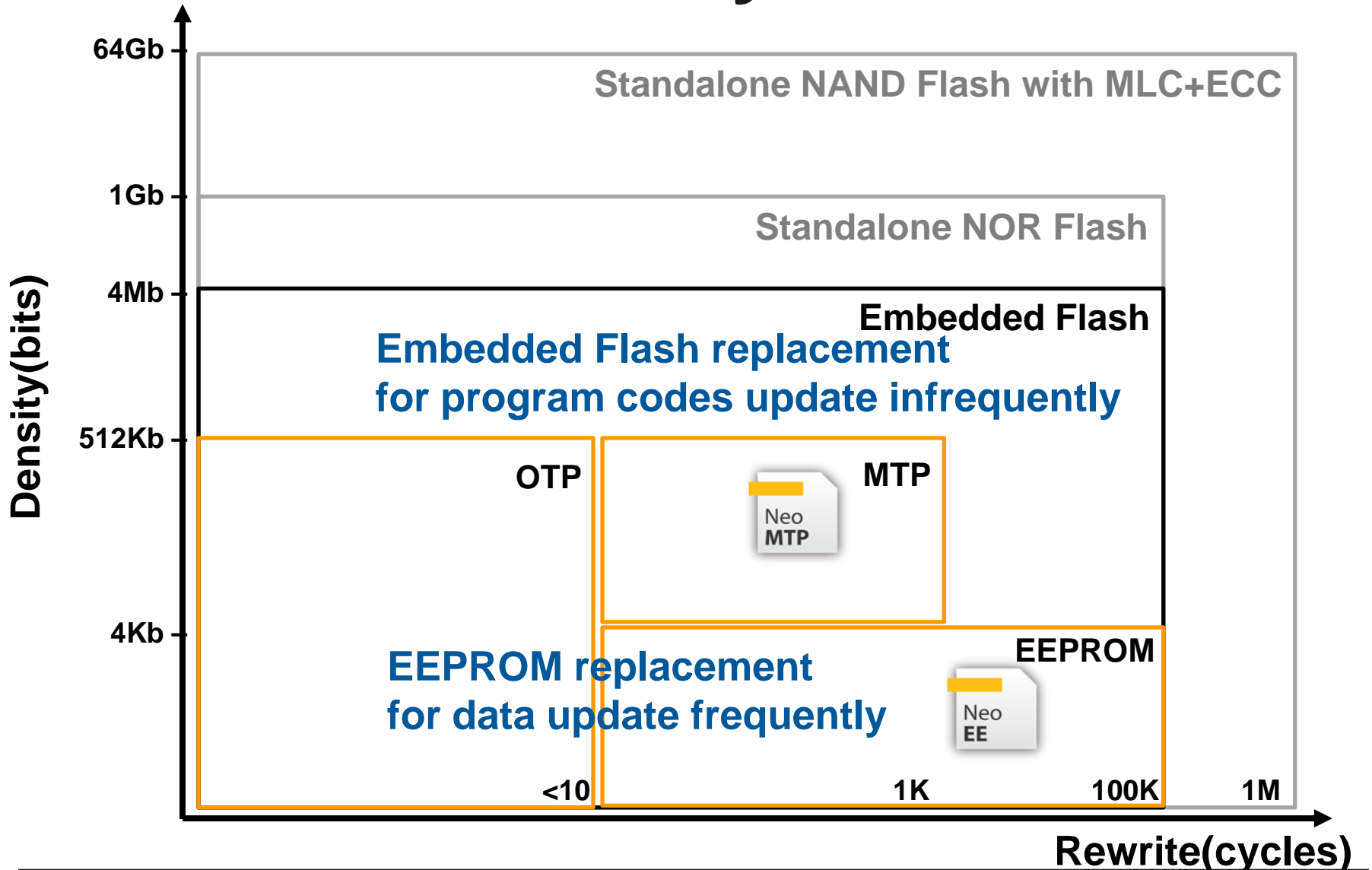**Embedded Wisely, Embedded Widely**

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Cautionary Statement

This presentation contains forward-looking statements, which are subject to risk factors associated with semiconductor and intellectual property business. It is believed that the expectations reflected in these statements are reasonable. But they may be affected by a variety of variables, many of which are beyond our control. These variables could cause actual results or trends to differ materially which include, but are not limited to: wafer price fluctuation, actual demand, rapid technology change, delays or failures of customers' tape-outs into wafer production, our ability to negotiate, monitor and enforce agreements for the determination and payment of royalties, any bug or fault in our technology which leads to significant damage to our technology and reputation, actual or potential litigation, semiconductor industry cycle and general economic conditions. Except as required by law, eMemory undertakes no obligation to update or revise any forward-looking statements, whether as a result of new information, future events, or otherwise.
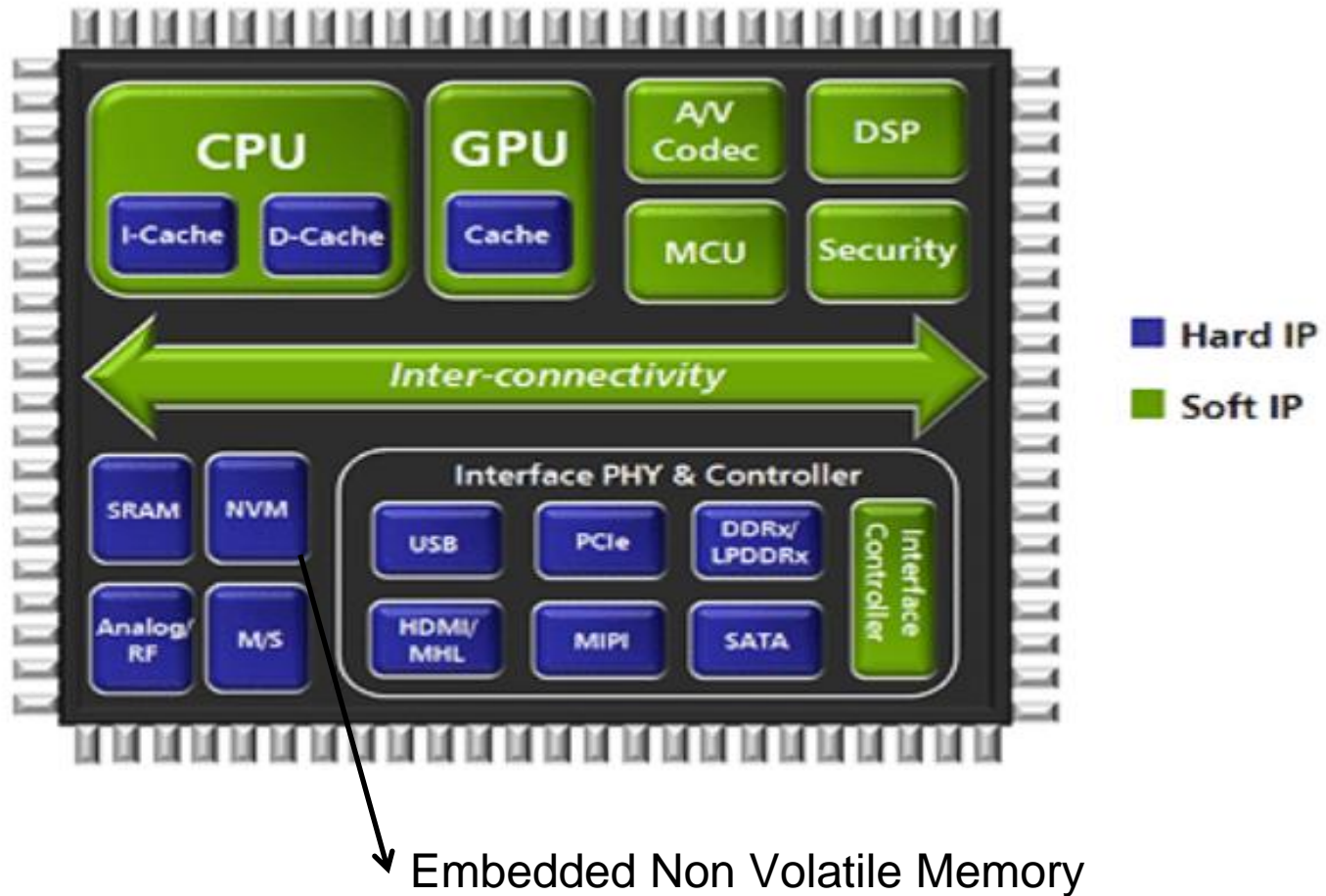
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Outline

- **Business Model**

- **Review of Operations**

- **Growth Opportunity and Future Outlook**

- **Q & A**

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Nonvolatile Memory Classifications

Density(bits)

- 64Gb — Standalone NAND Flash with MLC+ECC
- 1Gb — Standalone NOR Flash
- 4Mb — Embedded Flash

**Embedded Flash replacement
for program codes update infrequently**

- 512Kb — OTP / MTP

Neo MTP

- 4Kb — EEPROM

**EEPROM replacement
for data update frequently**

Neo EE

<10   1K   100K   1M

Rewrite(cycles)

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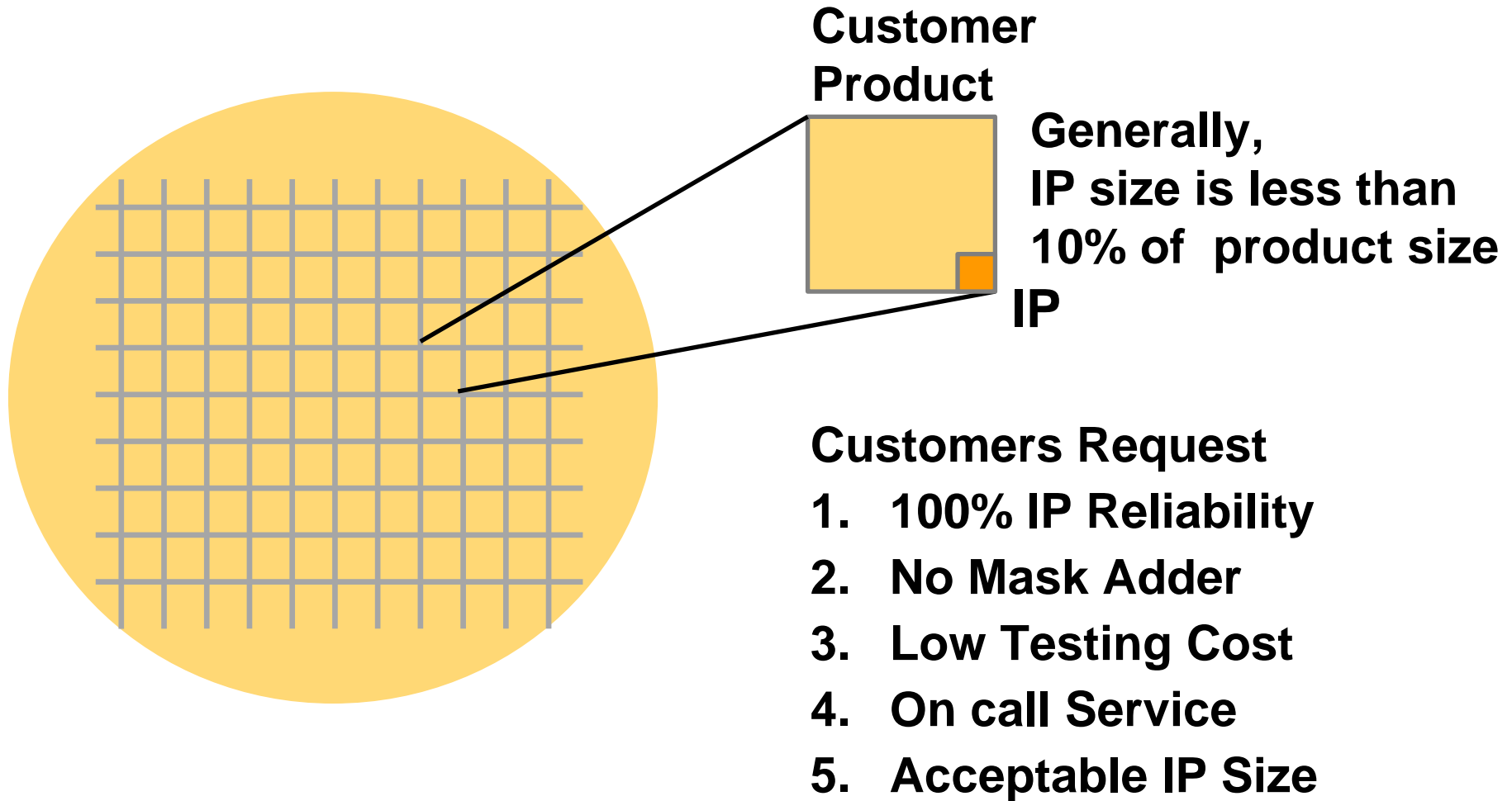
SOC Block Diagram

Embedded Non Volatile Memory

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Embedded NVM Technologies

	ROM	eFuse (OTP)	Antifuse (OTP)	CMOS Floating Gate (OTP)	CMOS Floating Gate (MTP)	Embedded Flash
Cell Structure	Transistor	Poly Fuse	Antifuse	Floating Gate	Floating Gate	Floating Gate
Standard CMOS Compatible	Yes	Yes	Yes	Yes	Yes	No
Bitcell Area	< 1	50	1	2	4	1
Endurance	No	No	< 10	< 10	10K-100K	100-1000K
Density	4Kb-1Mb	256bit-4Kb	16bit-1Mb	16Kb-1Mb	1Kb-2M	64Kb-4Mb
Security	Low	Low	High	High	High	High
Additional Steps	None	None	None	None	None	+10 Mask

- ROM not programmable, eFuse cannot scale beyond 16Kb, embedded flash expensive and cannot scale after 40 nm
- eMemory's IPs: OTP (antifuse, floating gate) and MTP (floating gate)

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Considerations for IP Adoption

Customer Product

Generally, IP size is less than 10% of product size

IP

Customers Request
1. 100% IP Reliability
2. No Mask Adder
3. Low Testing Cost
4. On call Service
5. Acceptable IP Size

Inside Nonvolatile Memory IP

Program, Erase and Read operation control

Where data is stored. Each cross point has a memory cell.

X-Decoder & Control Circuit

Memory Cell Array

Power supply for operations

Power

Y-Path

Data input & output

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Crossing the Chasm

Customers

NeoBit

NeoFuse

NeoEE
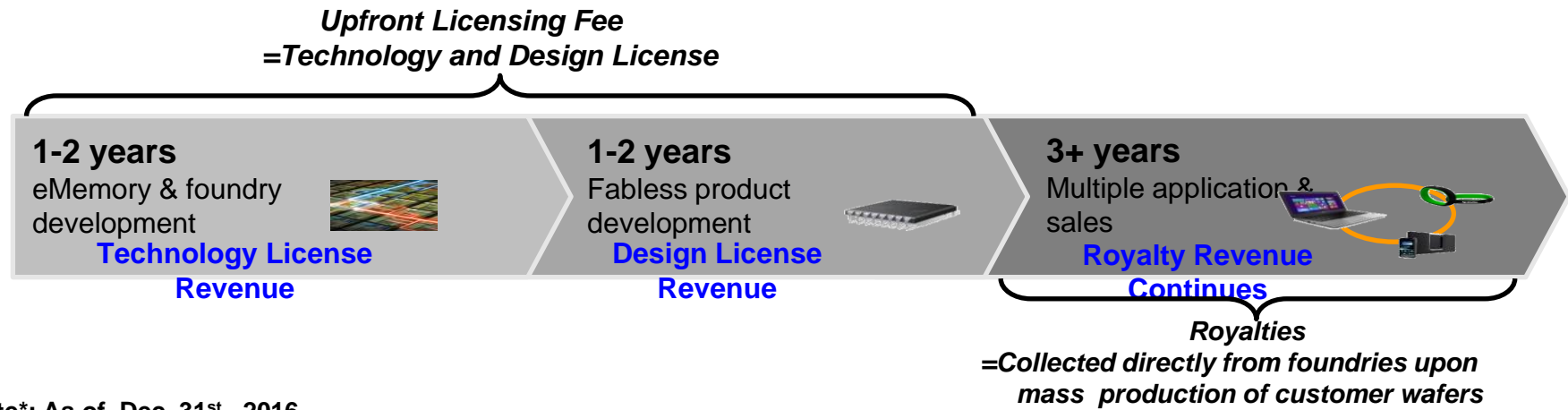
NeoMTP

NeoFlash

Time
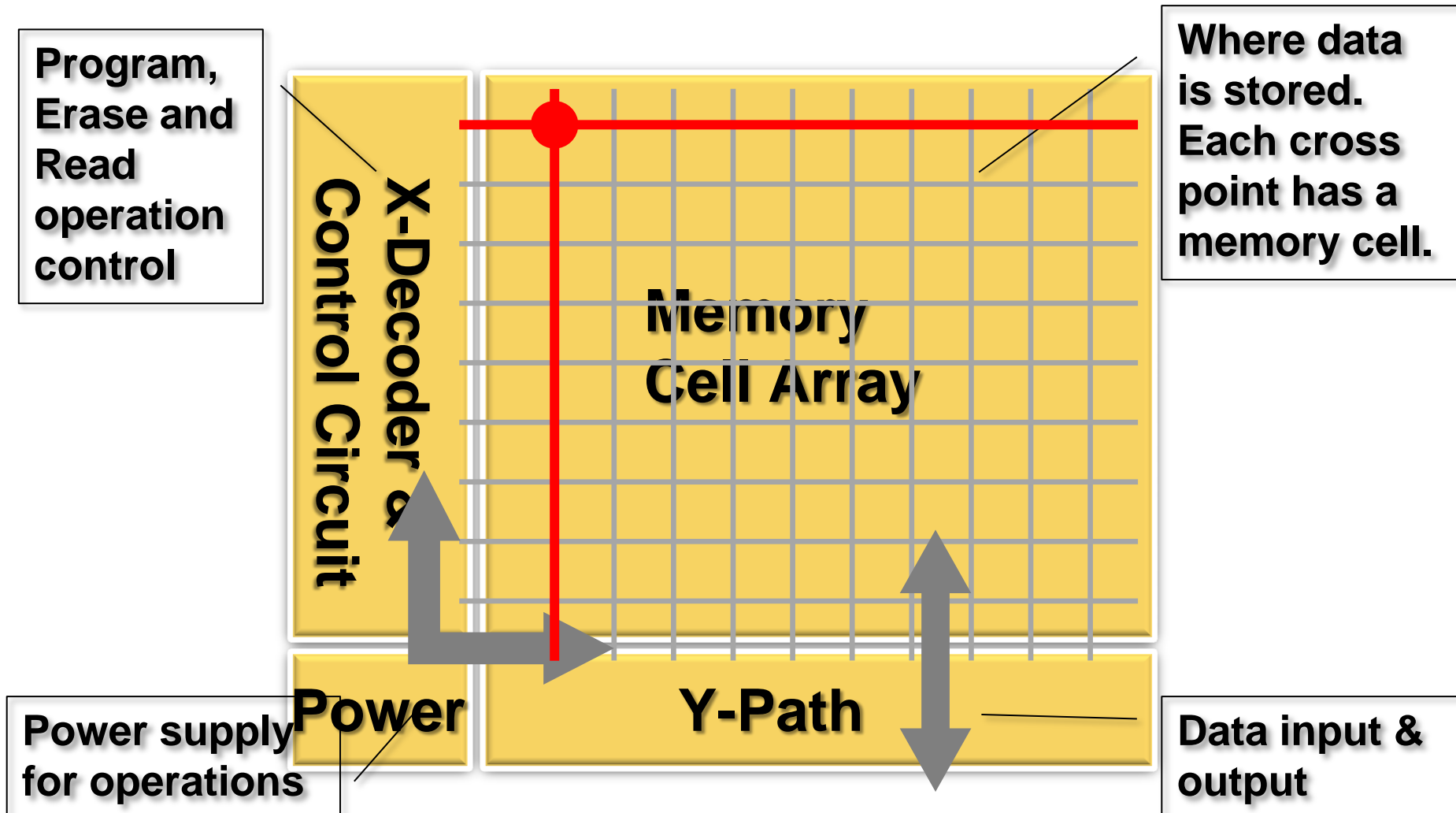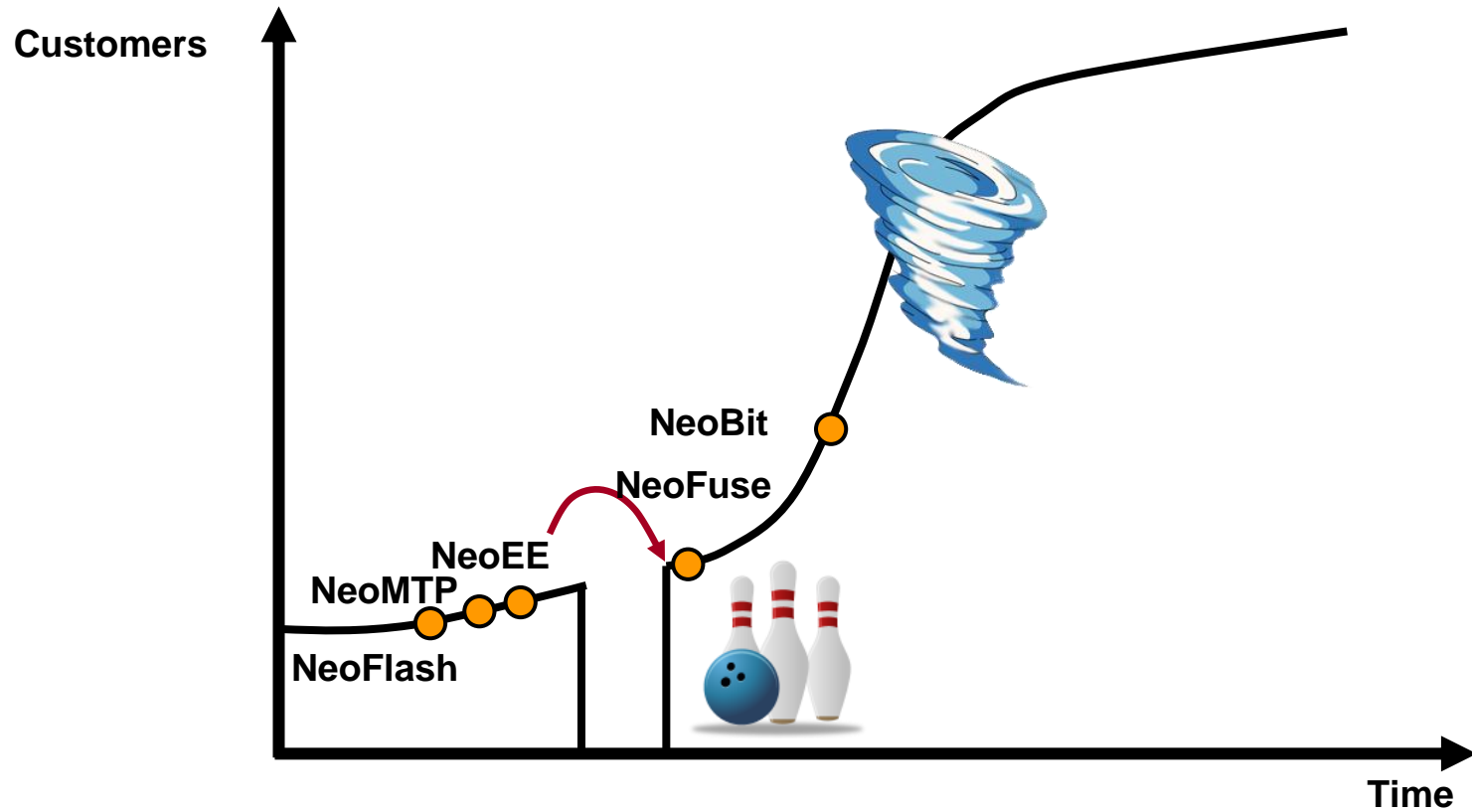
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Business Model

- **Founded in 2000. First customer engaged in 2002. Achieved profitability in 2005 and IPO in 2011. The largest logic non-volatile memory IP company, 232 employees (162 R&D)*.**

- **Since its IPO, the company initiated no new fund raising or bank debt, and has distributed in excess of 100% of earnings in cash dividends.**

- **Growth Indices: 1) No. of on-going technology platforms**
  2) No. of design licenses
  3) Royalty

Upfront Licensing Fee
=Technology and Design License

1-2 years
eMemory & foundry development
Technology License Revenue

1-2 years
Fabless product development
Design License Revenue

3+ years
Multiple application & sales
Royalty Revenue Continues

Royalties
=Collected directly from foundries upon mass production of customer wafers

Note*: As of Dec. 31st , 2016

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Worldwide Customers

Foundry

tsmc · UMC · VIS · SILTERRA · H&S 华虹宏力 · GLOBALFOUNDRIES · SMIC · MagnaChip · Maxchip 鉅晶電子 · ROHM SEMICONDUCTOR · SK hynix · Dongbu HiTek · HEJIAN · FUJITSU · Powerchip 力晶科技 · CSMC A LEADING ANALOG FOUNDRY · HLMC · asmc Advanced Semiconductor Manufacturing Corporation Limited · Altis

IDM

FUJITSU · OKI · MITSUMI · MITSUBISHI ELECTRIC Changes for the Better · JRC · MAXIM · RICOH · RENESAS · SII · TOSHIBA · ON Semiconductor · NXP

	Taiwan	China	Korea	Japan	North America	Europe	Others
Foundry	5	7	3	3	1	2	1
IDM	0	0	0	8	2	1	0
Fabless	264	496	66	51	226	111	50

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Patent Portfolio

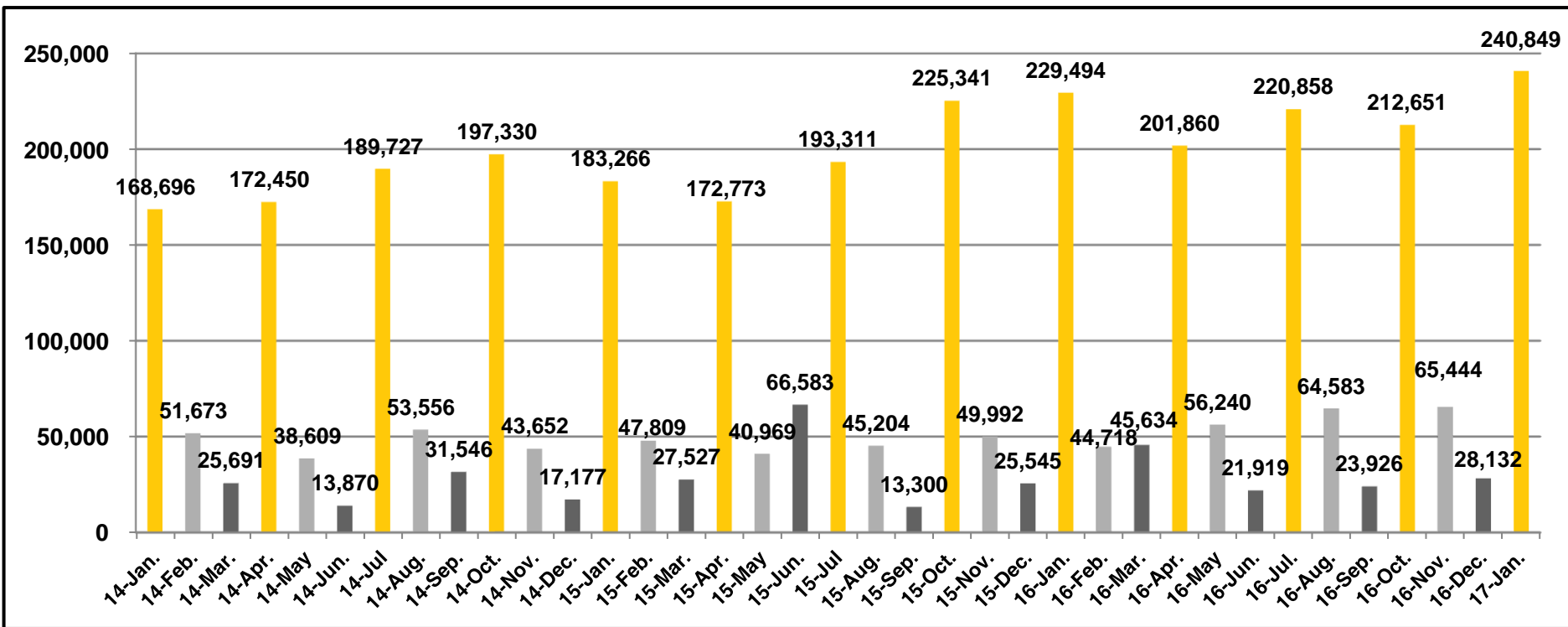|	Q3 16	Q4 16	Diff.
Pending	204	218	+ 14
Issued	371	389	+ 18
Total	575	607	+ 32

Note*: As of Dec. 31st, 2016

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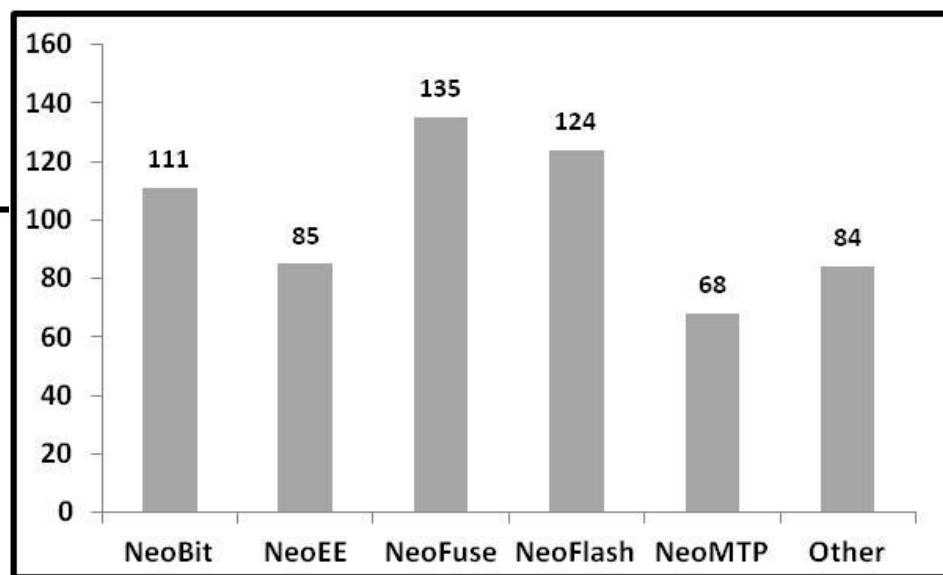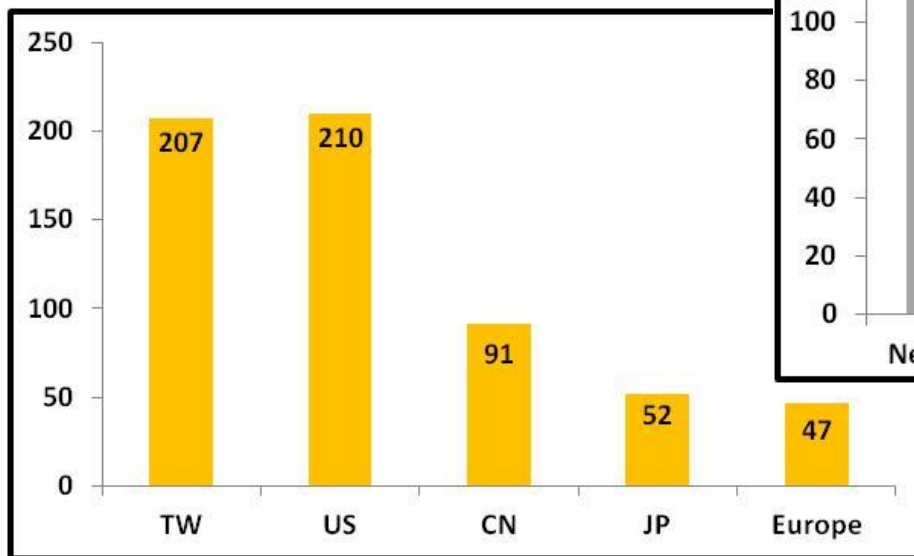
Quarterly Revenue Pattern

- **The quarterly royalty from most of foundries are collected at first month of each quarter and from some other foundries are collected at second month, and none at third month.**

Unit：NTD Thousands

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Q4 Revenue Breakdown

Unit: NTD thousands

	Q4 2016	Q3 2016	QoQ	Q4 2015	YoY	2016	2015	YoY
Licensing	79,684	86,712	-8.10%	69,307	14.97%	330,087	267,512	23.39%
Royalty	226,543	222,655	1.75%	231,571	-2.17%	885,372	824,108	7.43%
Total	306,227	309,367	-1.01%	300,878	1.78%	1,215,459	1,091,620	11.34%

Unit: Number of contracts

		Q4 2016	Q3 2016	2016	2015
Technology Licenses		10	6	43	28
Design Licenses	**NRE**	12	18	56	57
	Usage	73	81	311	349

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Financial Income Statement

(Unit: NTD thousands)	Q4 2016	Q4 2015	% change	2016	2015	% change
Revenue	306,227	300,878	1.8%	1,215,459	1,091,620	11.3%
Gross Margin	100%	100%	-	100%	100%	-
Operating Expenses	171,681	156,216	9.9%	685,650	570,403	20.2%
Operating Margin	43.9%	48.1%	-4.2ppts	43.6%	47.7%	-4.1ppts
Net Income	132,361	128,090	3.3%	534,917	479,111	11.6%
Net Margin	43.2%	42.6%	+0.6ppts	44.0%	43.9%	+0.1ppts
EPS (Unit: NTD)	1.75	1.69	3.6%	7.06	6.32	11.7%
ROE	28.3%	28.4%	-0.1ppts	28.6%	26.6%	+2.0ppts

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Technology License

Unit: Number of contract

Year	2013	2014	2015	2016
License number	19	21	28	43

Note: The terms (including number of process platforms and licensing fees) for each technology license are set contractually. Payments are made according to set milestones, and there are no particular seasonal factors involved.

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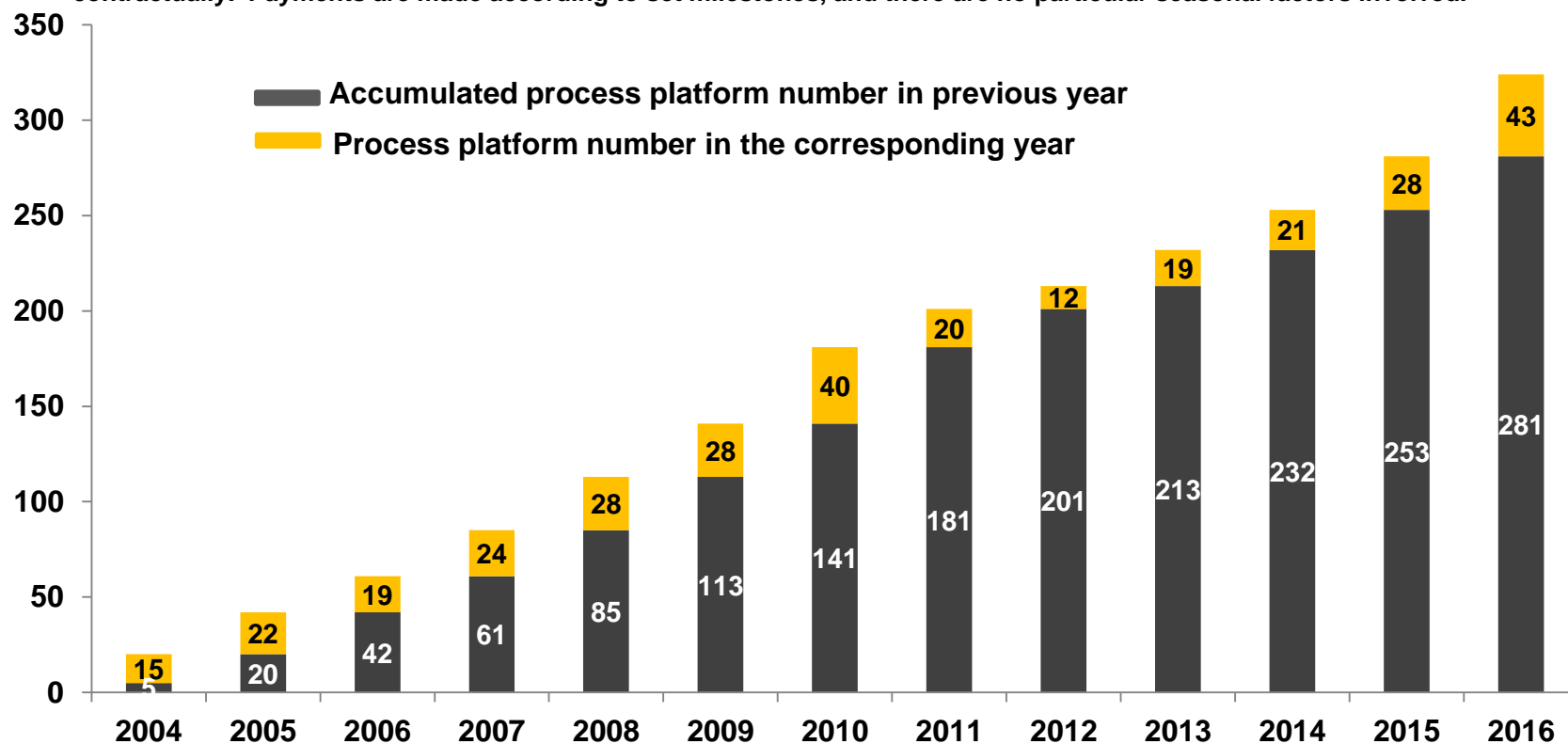
Current Technology Development Platforms

- **Total (As of Dec.) : 104**

- **19 for NeoBit, 43 for NeoFuse, 22 for NeoEE, and 20 for NeoMTP.**

	7/10nm	14/16nm	28nm	40nm	55/65nm	80/90nm	0.11~0.13um	0.15~0.18um	>0.25um
NeoBit	-	-	-	-	-	-	6	13	
NeoFuse	2	3	8	6	10	5	6	3	-
NeoFlash	-	-	-	-	-	-	-	-	-
NeoEE	-	-	-	-	-	-	5	17	-
NeoMTP	-	-	-	-	1	2	5	12	-

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Current Technology Development Platforms

12" Fabs	Production	Development	NVM Type	Process Type
7/10nm	0	2	OTP	FF
14/16nm	1	3	OTP	FF+
28nm	6	8	OTP	LP/HPM, HLP/HPM, LPS
40nm	4	6	OTP, MTP	HV-DDI, LP
55/65nm	14	11	OTP, MTP, Flash	LP, HV-DDI, HV-OLED, DRAM, CIS
80/90nm	6	7	OTP, MTP	HV-DDI, HV-OLED, LP
0.13/0.11um	8	2	OTP, Flash	HV-DDI, BCD, Generic
0.18um	1	0	OTP	BCD

8" Fabs	Development	NVM Type	Process Type
0.13/0.11um	20	OTP, MTP, Flash	HV-DDI, BCD, LP, RF, CIS, LL
0.18/0.16/0.152um	45	OTP, MTP	Generic, LP, LL, MR, HV, Green, BCD
0.25um	0	OTP, MTP	BCD
0.35um	0	OTP	UHV

Note*: As of Dec. 31st, 2016

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Quarterly Design Licensing (New Tape Out)

- Total 367 NTO as of 2016(406 @2015, 445 @2014, 393 @2013, 303 @2012)

	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4
	2012				2013				2014				2015				2016			
NRE	7	15	10	10	7	14	18	12	33	12	22	15	21	17	10	9	12	14	18	12
Usage	62	68	63	68	73	69	88	112	90	86	88	99	82	87	76	104	63	94	81	73
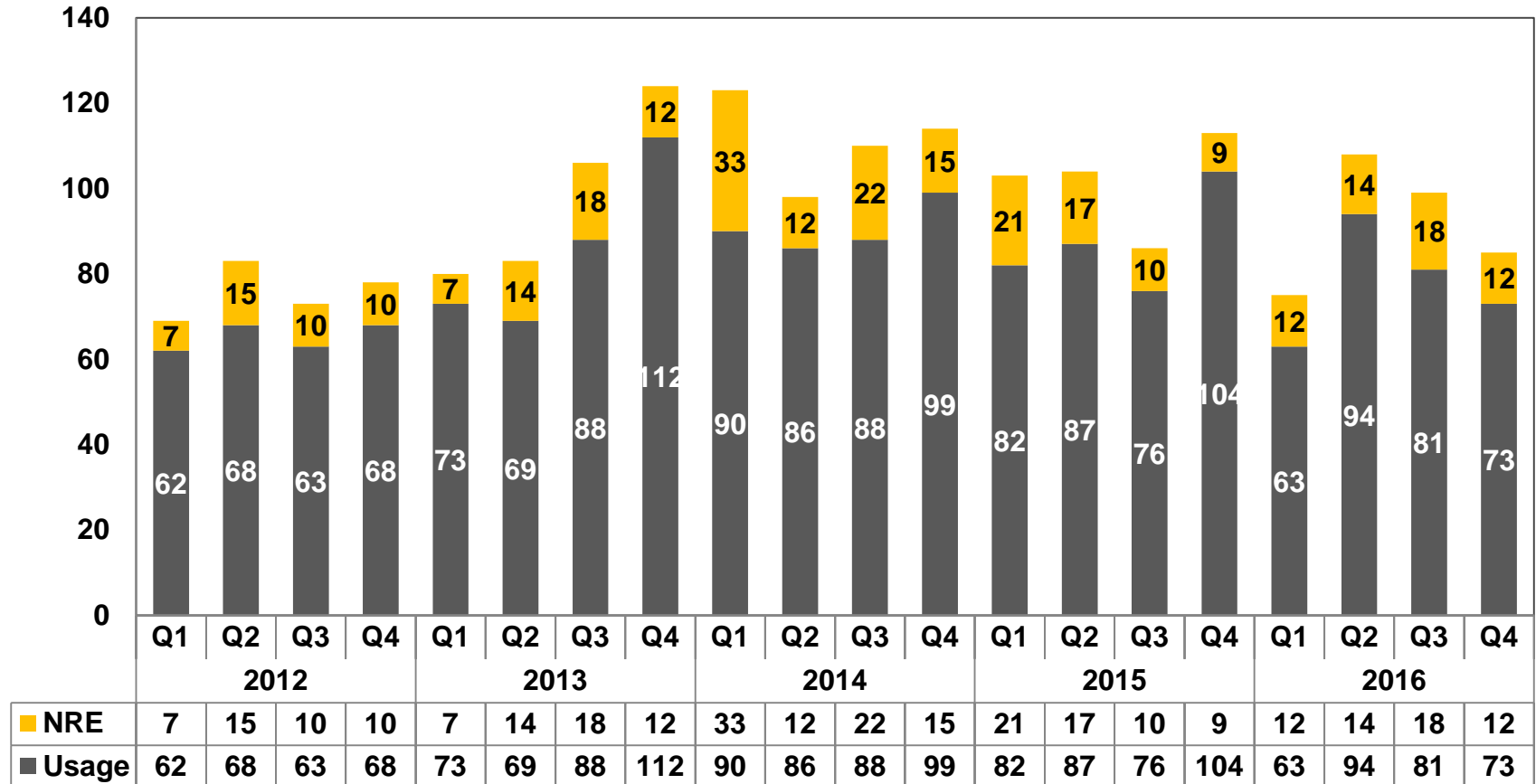
Note*: As the applications of MCU at several foundries have gradually entered mass production, and the business model of the main foundry partner which provides green process has shifted to — eMemroy licenses IP cell to the foundry for it to provide direct design service to customers — as the result, the new tape out number of MCU has been affected, but the royalty coming from IP cell usage continues to roll in.
In summary, even the new tape out number of MCU is lower than before; the corresponding wafer output and royalty continue to grow.

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Cumulative Licenses Drive Future Royalties

Cumulative design licenses **> 3,522**

Legend:
- Design licenses in the corresponding year
- Cumulative design licenses
- Royalty

Royalty (NT $ million) values: 15, 65, 132, 201, 198, 331, 310, 426, 563, 758, 824, 885

Design licenses in the corresponding year: 68, 138, 226, 267, 281, 296, 258, 303, 393, 445, 406, 367

Cumulative design licenses: 68, 142, 280, 506, 773, 1,054, 1,350, 1608, 1911, 2304, 2749, 3155

Years: 2005, 2006, 2007, 2008, 2009, 2010, 2011, 2012, 2013, 2014, 2015, 2016

note 1: Due to the 2009 recession, royalty income was down annually 1.5%.
note 2: Pre-payment of royalty fees by a single customer contributed to 2010 annual growth of 67%,
        causing a drop of 6.3% in the following year, 2011.
note 3: CAGR for 2009-2013 was 30%.

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Wafer Production Volume
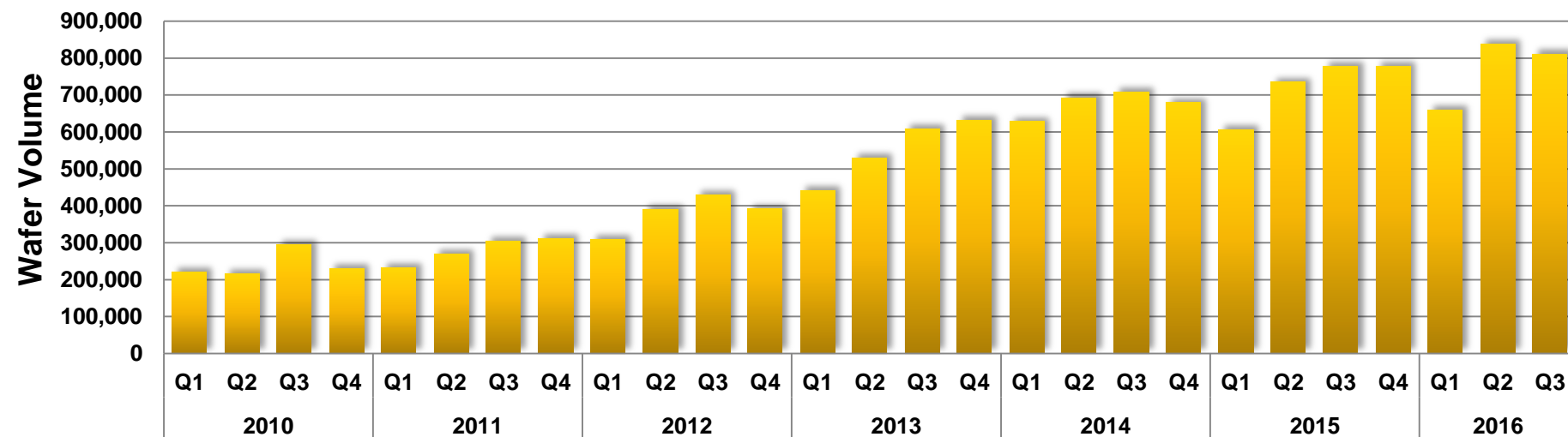
embedded eMemory IP in T Company ($revenue); * % of Process node in T company total revenue in Q4 2016

	Process node	*% of T	Q4 16	Q3 16	2016	2015
8"	0.25/0.35	2%	26.80%	26.44%	28.15%	33.49%
	0.15/0.18	10%	10.93%	13.07%	12.43%	8.73%
	0.11/0.13	2%	58.06%	40.96%	42.61%	29%
12"	90nm	5%	14.8%	3.83%	12.50%	19.85%
	65nm	11%	3.9%	3.85%	3.59%	0.55%
	40/45nm	12%	0	0	0.00%	0%
	28nm	24%	0.70%	0.61%	0.55%	0.05%
	16/20nm	33%	0%	0	0.00%	0%
8"		15%	18.60%	20.1%	18.86%	16.64%
12"		85%	1.56%	0.87%	1.44%	1.87%
Total		100%	4.12%	3.95%	4.27%	4.76%

Outline

- **Business Model**

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eMemory's NVM Technologies

- **Logic NVM portfolio offers one-stop-shop solution.**
  - › Compatible to any process
  - › Robust structure
  - › Low process cost
  - › Competitive macro sizes
  - › Easy integration
  - › Easy porting

eMemory's NVM Technology	OTP		MTP		
	NeoBit	**NeoFuse**	**NeoFlash**	**NeoEE**	**NeoMTP**
Product Type	OTP	OTP	Flash	EEPROM	MTP
Endurance (Cycles)	10	10	1K~10K	10K~100K	1K~10K
Additional Mask Steps	0	0	2-3	0	0
Technology	Floating gate	Anti-Fuse	SONOS	Floating gate	Floating gate
Scalability	Simple	Simple	Simple	Simple	Simple
Memory Density	HD < 512Kb GHD < 16Mb	< 4Mb	< 2Mb	< 4Kb	< 512Kb

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Applications by Technology

				12"					8"		
7nm	10nm	16nm	28nm	40nm	55/65nm	80/90nm	110/130nm	160/180nm	250nm	350nm

NeoBit

NeoFuse

NeoFlash

NeoEE

NeoMTP

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Opportunity at all Price Points

eMemory Inside today

Royalty

Opportunity

$400-700	$750-1,000	$1,000-4,000	$4,000-8,000
(0.5um-0.25um)	(0.18um-0.11um)	(90nm-55nm)	(40nm-16nm)

Average Selling Price of Wafer
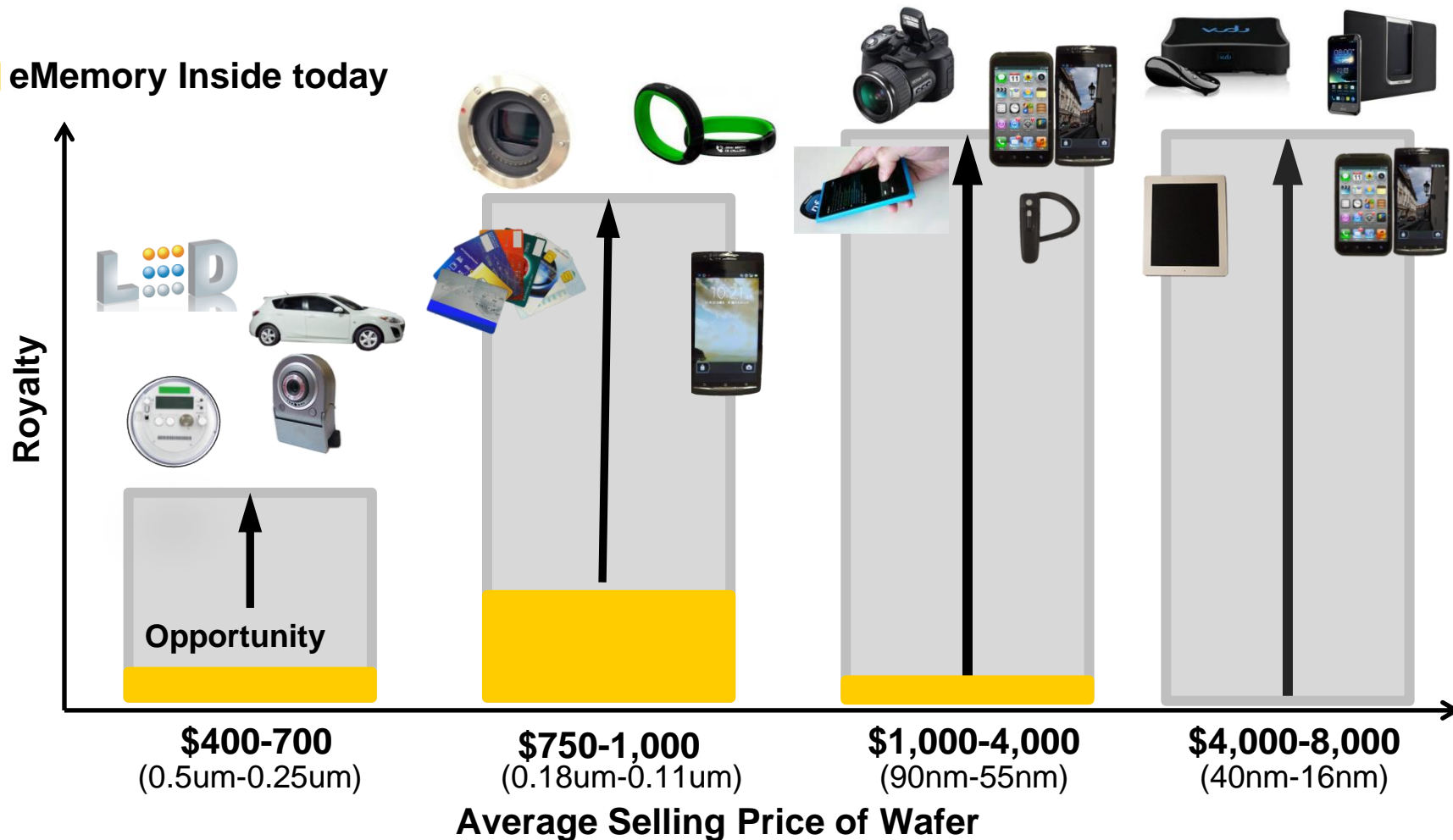
Note: 2.2 million 8" equivalent wafers with eMemory IP were shipped in 2013. (~5% of WW foundry shipment)

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eMemory IP in Smart Phone

Neo **Flash**

Neo **MTP**

Capacitive Touch Panel Controller

Neo **Fuse**

Neo **EE**

Neo **Bit**

- Ambient Sensor
- Proximity sensor

Neo **Bit**

PMIC/PMU

- Accel.-sensor
- Mag.-sensor
- Gyro-sensor

Neo **Bit**

NFC

- Base Band

Neo **Fuse**

Neo **EE**

- Application Processor

Battery

LCD Driver

Connector

Camera Module

Fuel Gauge

Neo **Flash**

Neo **Fuse**

Neo **MTP**

Neo **Bit**

Neo **Bit**

Neo **EE**

Neo **Fuse**

Neo **MTP**
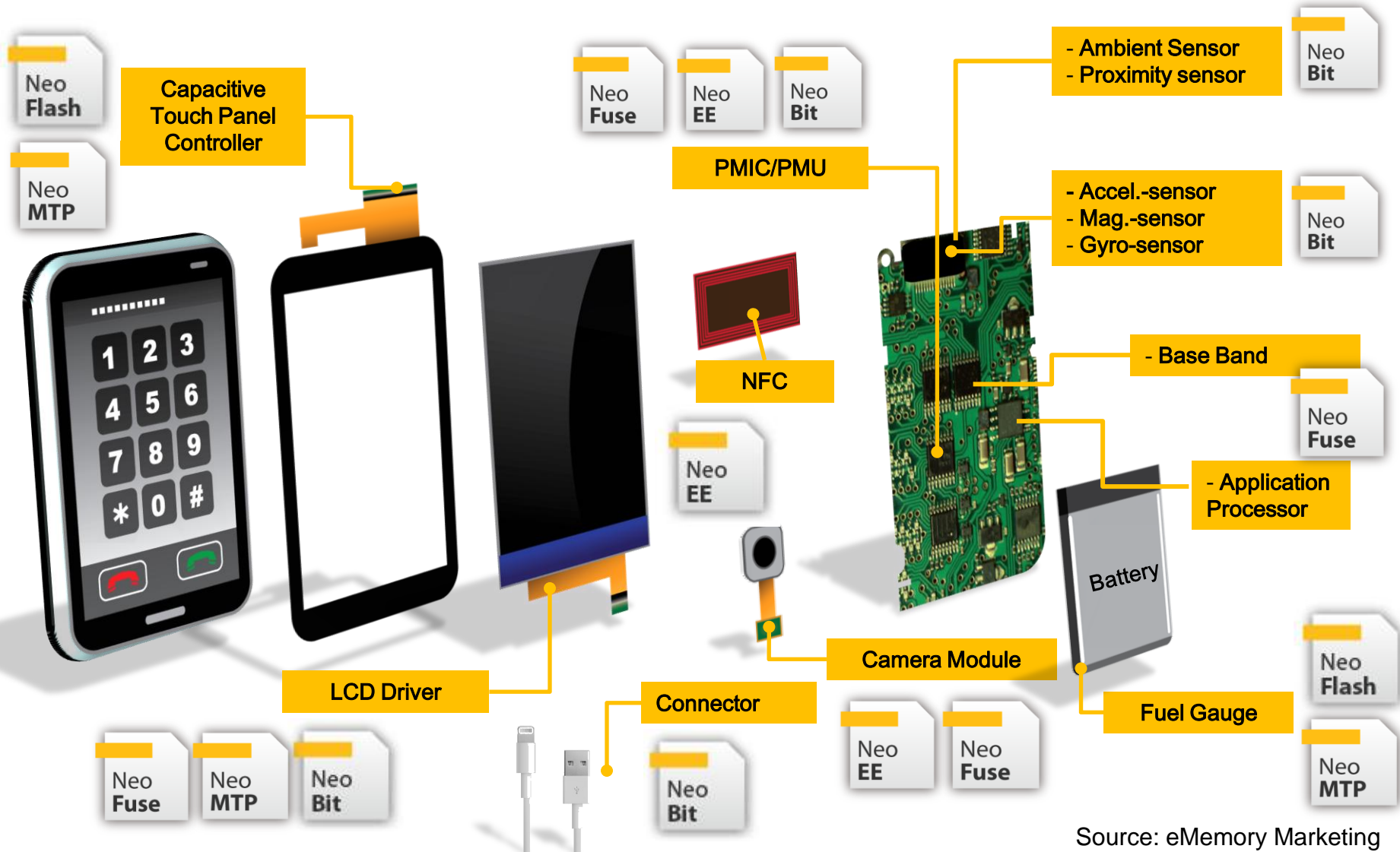
Source: eMemory Marketing

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Benefits from Using eMemory IPs

Design-in for
1. Trimming
2. Parameter Setting
3. Code Storage
4. Identification Setting
5. Encryption
6. Function Selection

Package/FT level
1. Trim : SPEC shift
2. Parameter Setting : cross chip optimization
3. Identification Setting : manufacturer resume
4. Function Selection : setting for target market

CP Test

Package/FT

System Assembling

IC Design

NVM IP

CP level
1. Trim : output voltage or current
2. Parameter Setting : default value
3. Code Storage : default F/W code
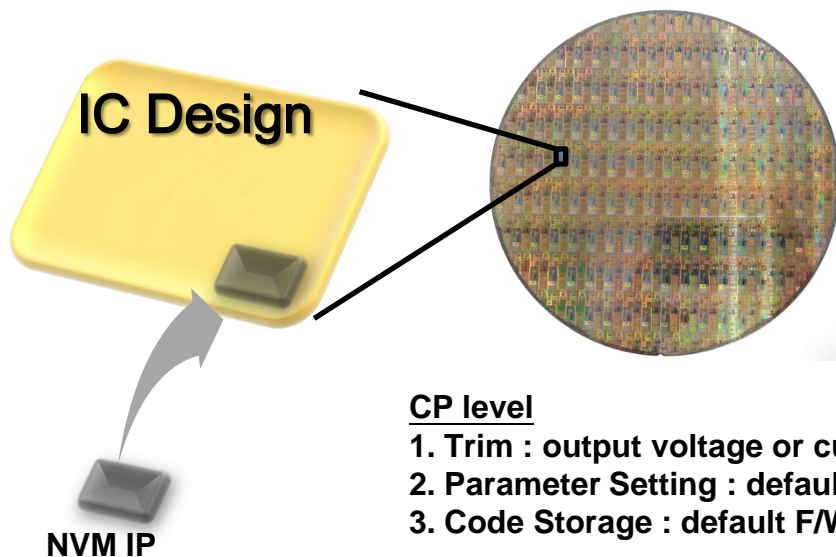
System Assembling
1. Parameter Setting : cross chip optimization
2. Code Storage : F/W code modification
3. Identification Setting : manufacturer resume
4. Encryption : Security algorithm or key storage

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Invisibility for Security

- **Provide "Invisible Hardware Key" for invisible storage**

- **Prevent reverse-engineering to detect content of security key**

- **Protect firmware and hardware of ICs from pirating**

- **Extend & protect customer's business**

eFuse Key: Data is easily observed

Invisible Hardware Key : Data is hard to be detected

Floating Gate

Anti-Fuse
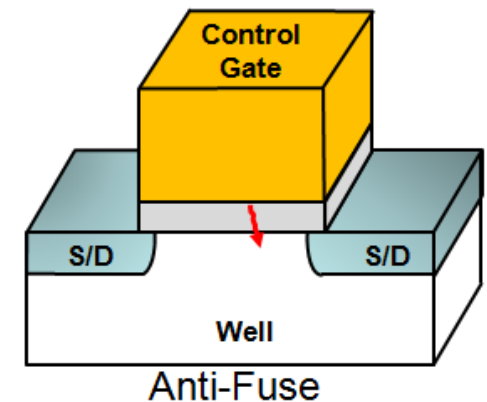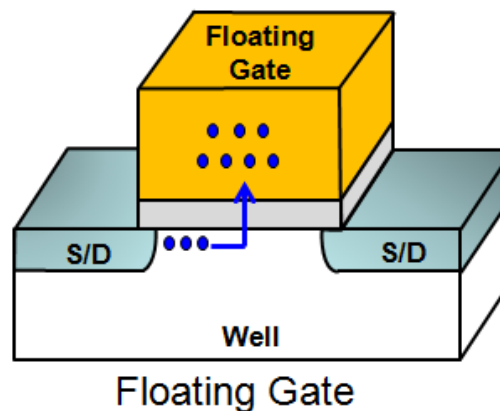
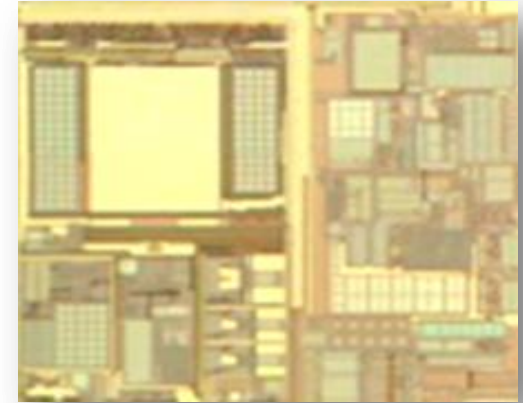# Security & Protection

Authorized Product

Fake Product

reverse copy

re-produce

without protection

reverse copy

re-produce

with protection
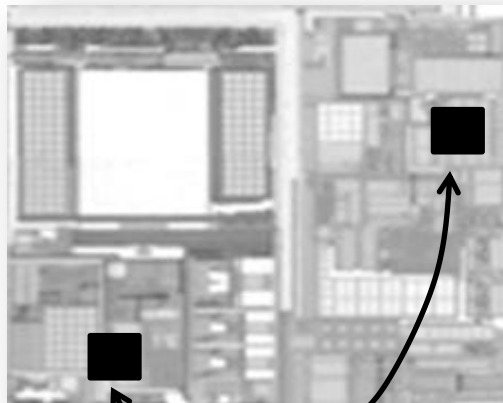
Security IP/Code by Authorized Use

Can NOT Work w/o Security IP/Code

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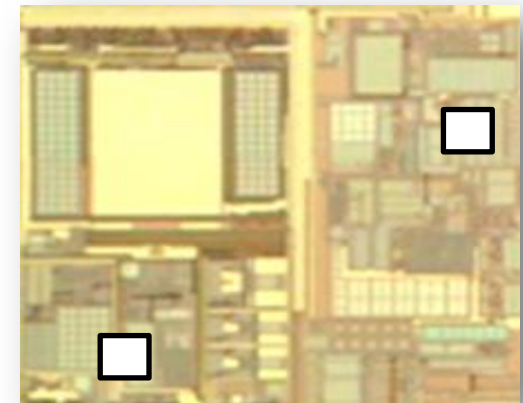
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OTP for security storage

Private OTP/Fuses

HW Constraints

OTP Wrapper

Interrupt(s)

CryptoManager

Extractor

Feature activation
Configuration
Personalization
(SoC Consumers)

JTAG/Scan

Bus

CPU

Direct key delivery
(SoC Crypto Cores)
Ex/ SD encryption,
HDCP, DTCP, DRM,
VPN, Payments,
Password Mgr.

**Reset, clock
powerdown**

BIST

**General I/F
(AMBA, APB,
or similar)**
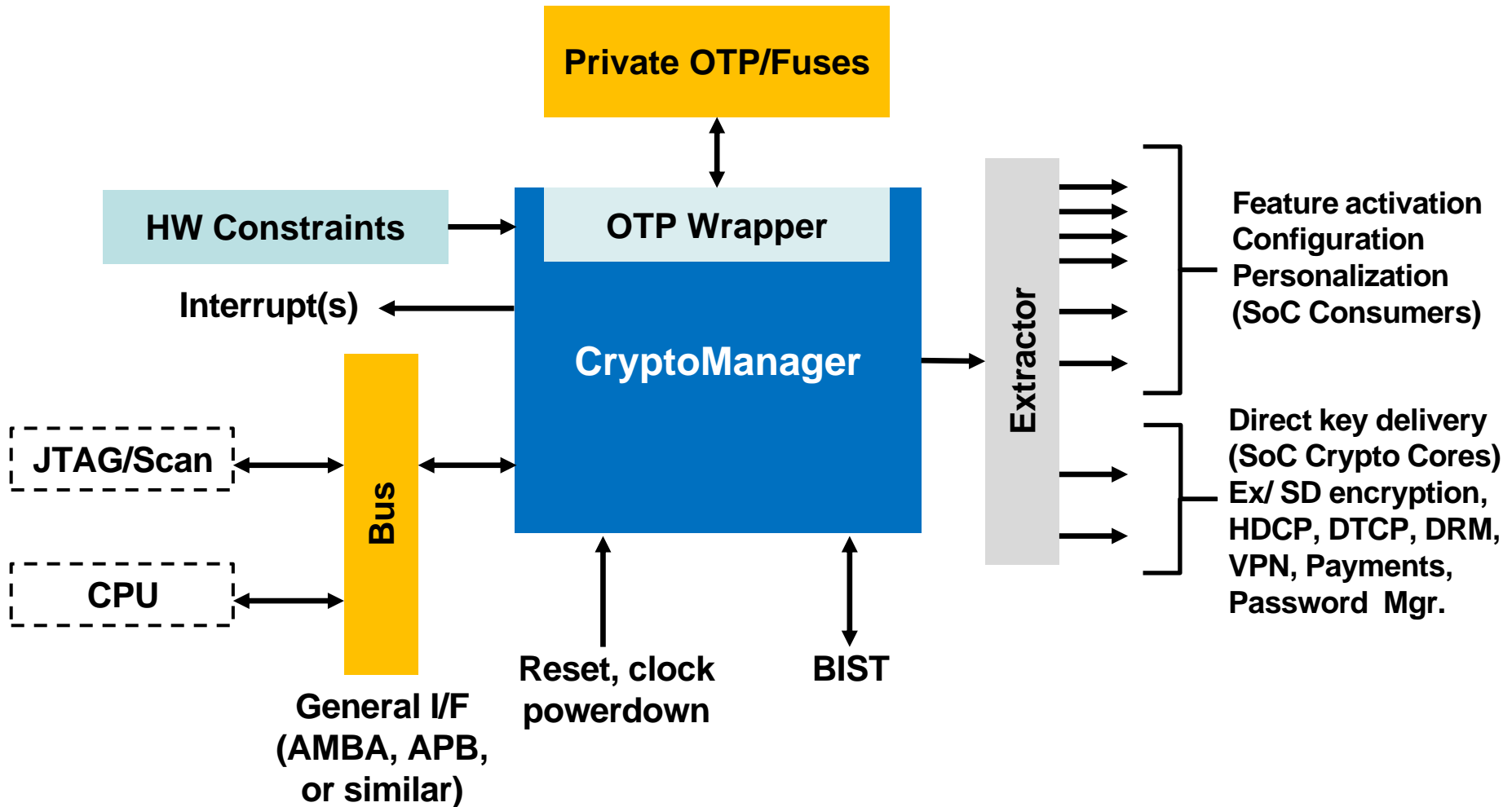
Source：Rambus crypto manager platform

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Security with eMemory IPs

Security for System Service

Neo **Fuse**　Neo **Bit**

HW-SW/FW Lock

Cloud Processing

HW Key

**ID & Authentication
Data Integrity
Access Control**

Neo **EE**　Neo **Bit**　Neo **Fuse**

SoC

Security Lock

**FW (OS) with
security key**

**HW Protection
Invisible Key for
Anti-Cloning**

Neo **Fuse**　Neo **Bit**

**Security IP/Code by
Authorized Use**

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NVM IP Demand in IoT

All Smart Systems

Basic Technology	Sensing	Embedded Processing	Connectivity

IC Types

Sensing	Embedded Processing	Connectivity	
Accelerometer	MCU	NFC	Cellular
Magnetometer	MPU	GPS	Sub-Gig
Gyroscope	Hybrid MCU/MPU	BT/BTLE	ZigBee
Pressure		Wi-Fi	RFID
Altimeter	Network Processor		
Temperature			

NVM IP Function

Encryption/Security	Function Selection	Trimming/Calibration
F/W code storage	Parameter Setting	ID Setting

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Autotronics with eMemory IPs

Intelligent drive Distronic system

Neo **Bit** Neo **Fuse**

Infotainment system

Neo **Bit** Neo **Fuse**

Sensor system

Neo **Bit** Neo **EE**

Auto parking system

Neo **Bit** Neo **Fuse**

Blind Spot Warning System Cockpit System

Neo **Bit** Neo **Fuse**

OBU & GPS

Neo **Bit** Neo **Fuse**

Keyless door

Neo **Bit** Neo **EE**

Rear view system

Neo **Bit** Neo **Fuse**

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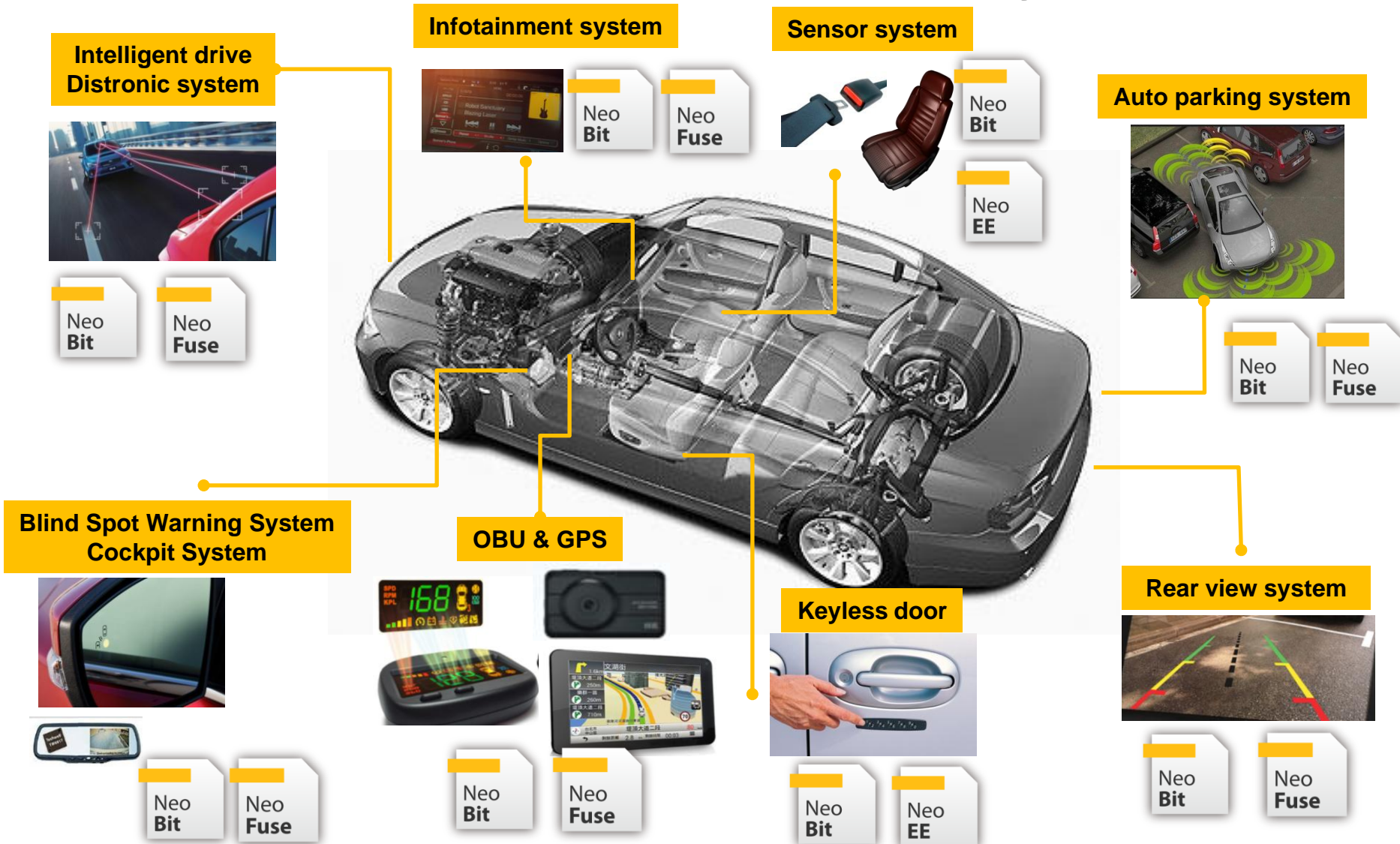
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Imager Module with eMemory IPs

VCM

IR Cut Filter

Lens

AF/OIS Controller (VCM Driver)

Neo **Fuse**　Neo **Bit**
Neo **EE**　Neo **MTP**

Image Sensor

Neo **Fuse**　Neo **Bit**

ISP

Neo **Fuse**　Neo **Bit**
Neo **EE**　Neo **MTP**

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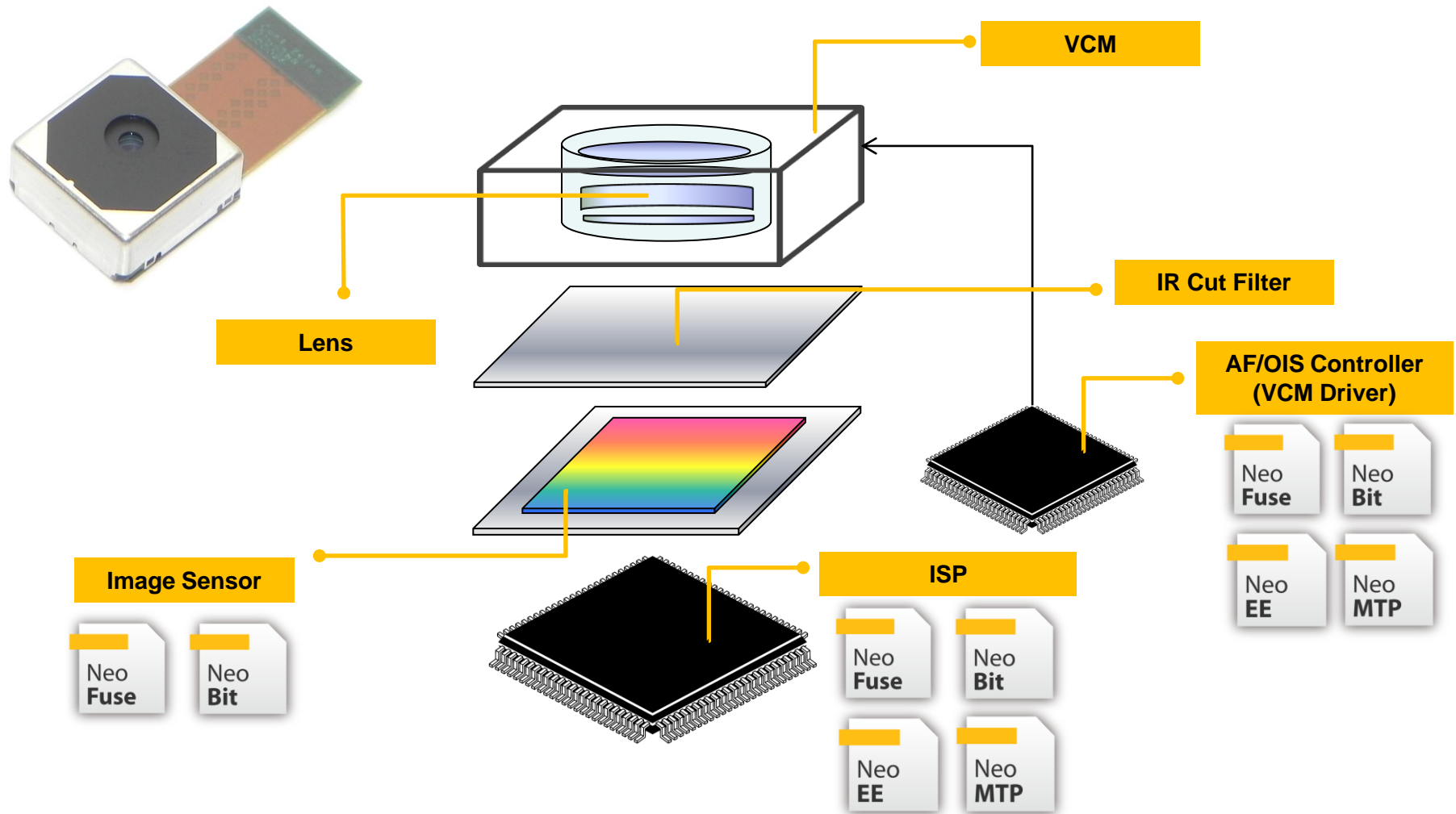
Advanced LCD Driver ICs

Process Technology : 0.11um HV/80nm HV/55nm HV

I/F
(LVDS, MIPI,…)

TCON

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Display Power

LED Backlighting

Gate Driver

LCD Display

VCOM Buffer

Source Driver

DDI

Neo Bit
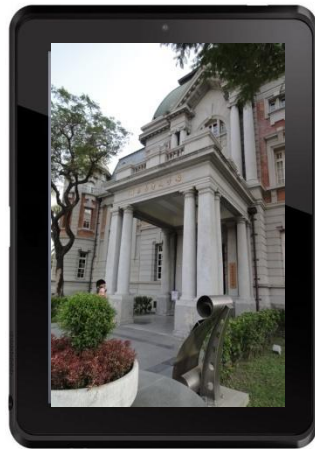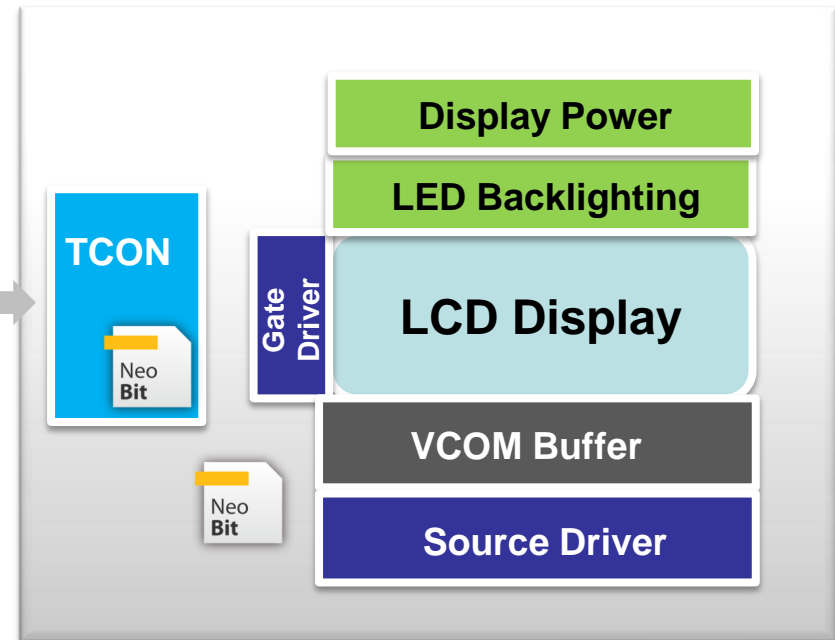
Density	Endurance	NVM Type	Purpose	NVM Usage		
2K8~4K8	1	OTP	Trimming	1. Accuracy enhancement		
				2. Mismatch cancellation		
			Code Storage	1. Gamma Correction Table		
				2. Timing Control Pattern		
				3. Color Engine Enhancement		

Power Management ICs for Baseband and Application Processor

Process Technology : Advanced 0.25um BCD/ 0.18um BCD/ 0.13um BCD
Mature 0.18um/0.16um/0.152um Logic
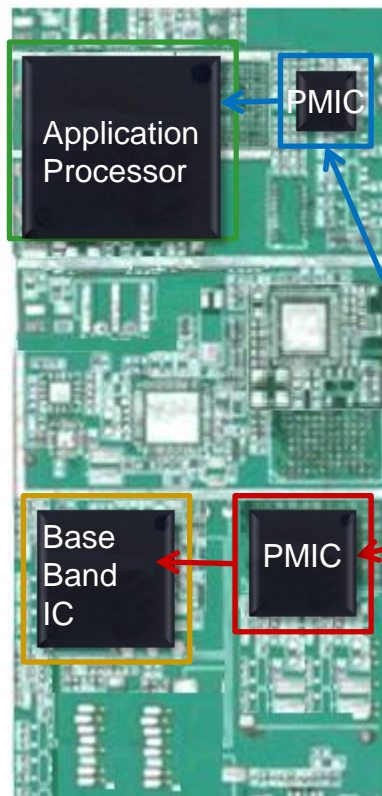
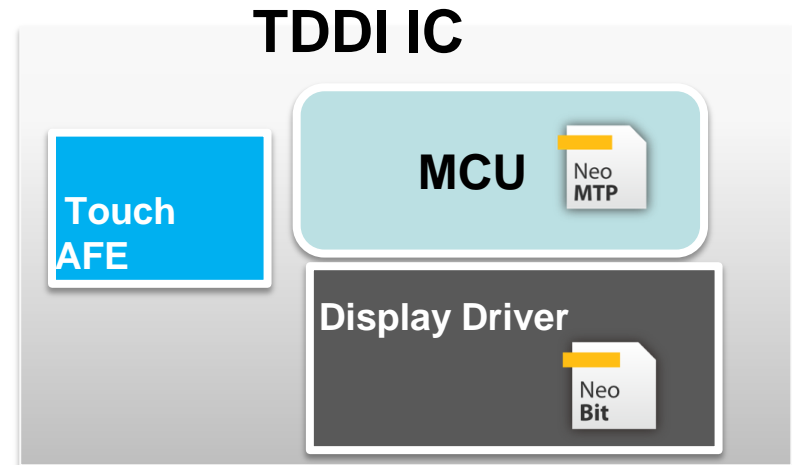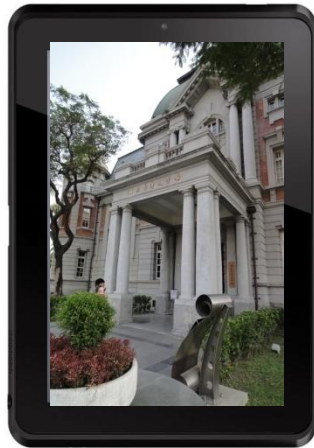| Density	NVM Type	Purpose	NVM Usage
2Kb~4Kb	OTP	Trimming	DC/DC, Bandgap
		Parameter Setting	Design flexibility & Performance optimization
		Code Storage	Start-up behavior & smart power saving algorithm

Application Processor

PMIC

Base Band IC

PMIC

PMIC Neo Bit

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Touch Panel Controller ICs

Process Technology : 0.16um HV/0.11um G

TPC

AFE

MCU

Neo Flash

Neo MTP

I/F Circuit

Density	Endurance	NVM Type	Purpose	NVM Usage
16K8~32K8	<1000	MTP	Code Storage	F/W code
			Parameter setting	Customized model and performance optimization

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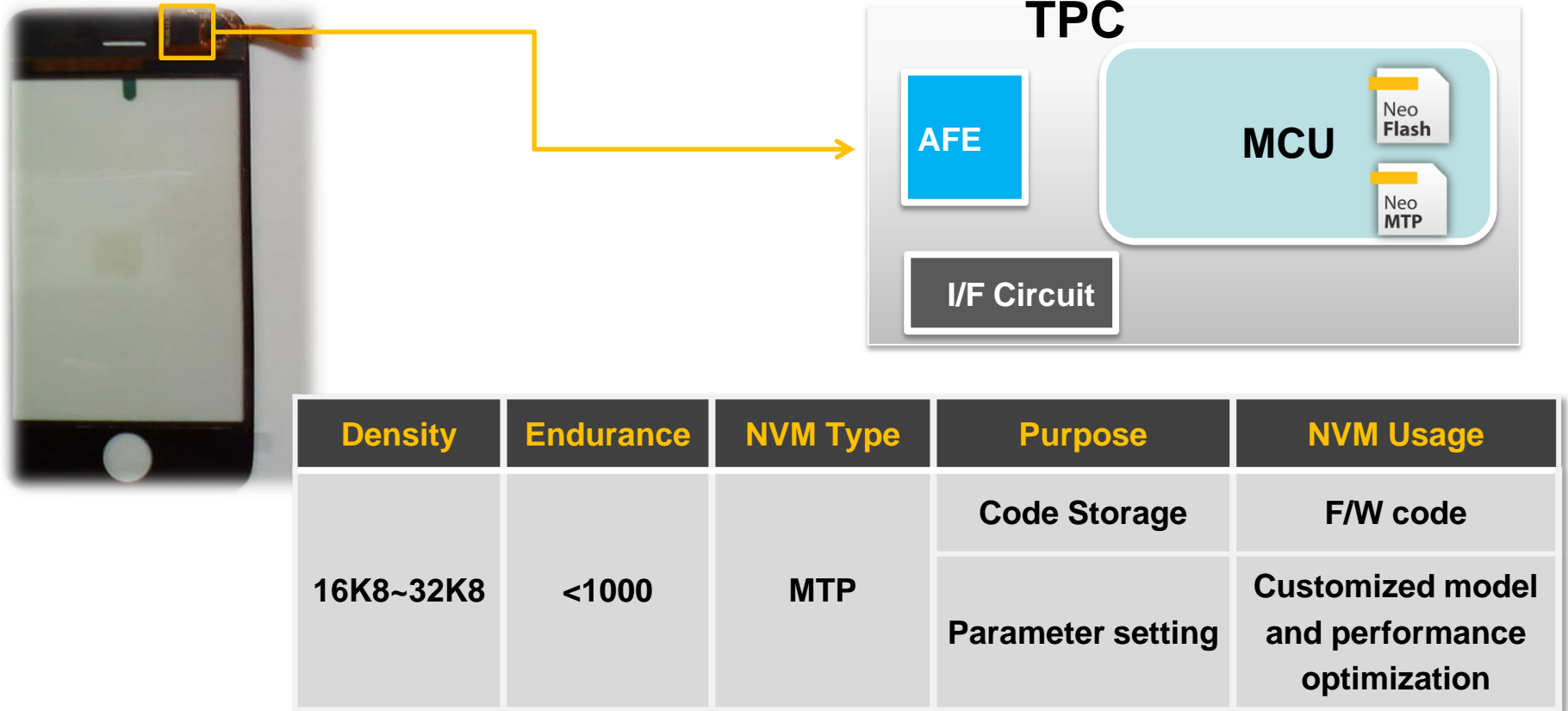
In-Cell Touch Panel Controllers ICs

Process Technology : 0.11um HV/80nm HV/55nm HV

TDDI IC

Touch AFE

MCU — Neo MTP

Display Driver — Neo Bit

Density	Endurance	NVM Type	Purpose	NVM Usage
2K8~4K8	1	OTP	Trimming	Accuracy
			Code Storage	Gamma Table
16K8~32K8	<1000	MTP	Code Storage	Touch F/W Code
			Parameter setting	Performance Optimization

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CMOS Image Sensor

Process Technology : 0.11um CIS/90nm CIS/65nm CIS

CIS SoC

Column S/H

Row Select

Image Array

AFE

Image Sensor Processor

Neo Fuse
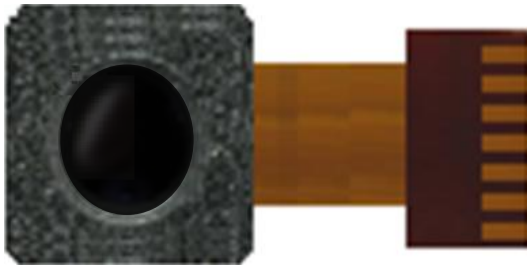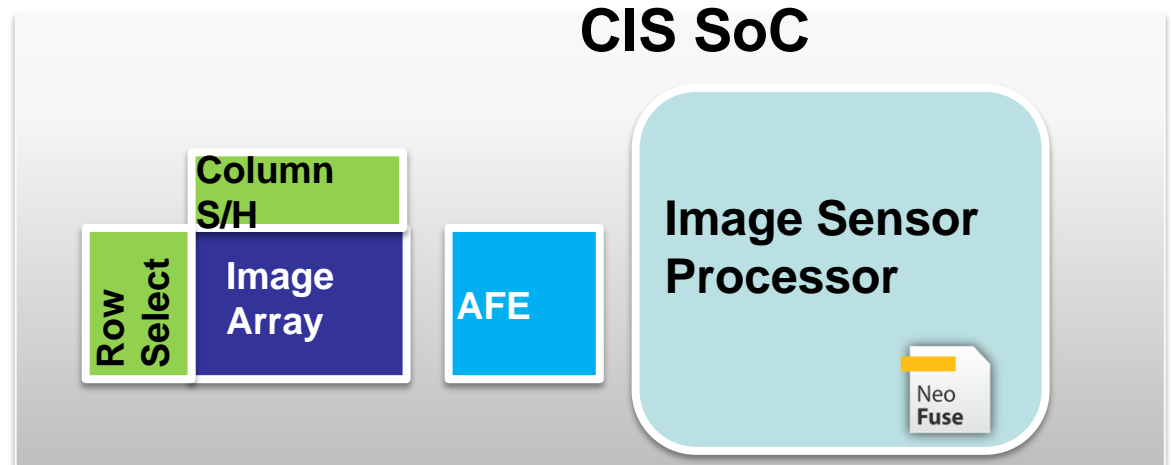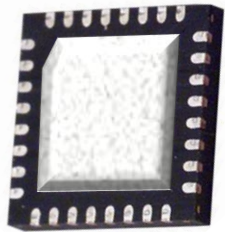
Density	Endurance	NVM Type	Purpose	NVM Usage
2Kb~4Kb	1	OTP	Identification Setting	Product Code
			Parameter Setting	Start-up Initial Setting
32K8	1	OTP/ROM	Code Storage	Boot Load

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MEMS

180/160/15x nm HV/Logic for MEMS Controller
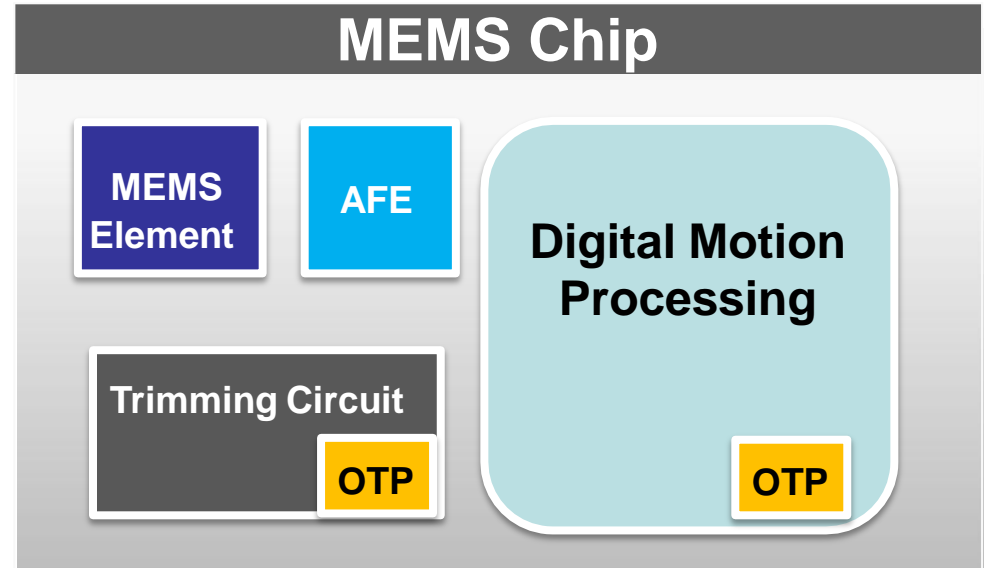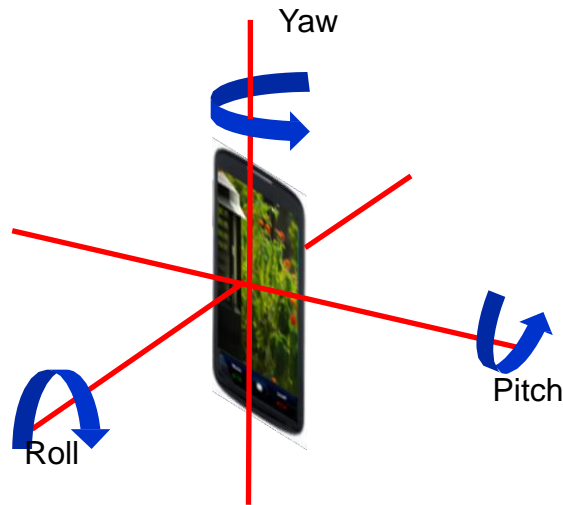
Density	NVM Type	Purpose	NVM Usage
2Kb~4Kb	OTP	Trimming	Factory trimming
		Parameter Setting	Signal filtering
		Code Storage	Geometric computation

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Replacement of Embedded Flash for Competitiveness Improvement

MCU

product design & manufacturing by embedded Flash
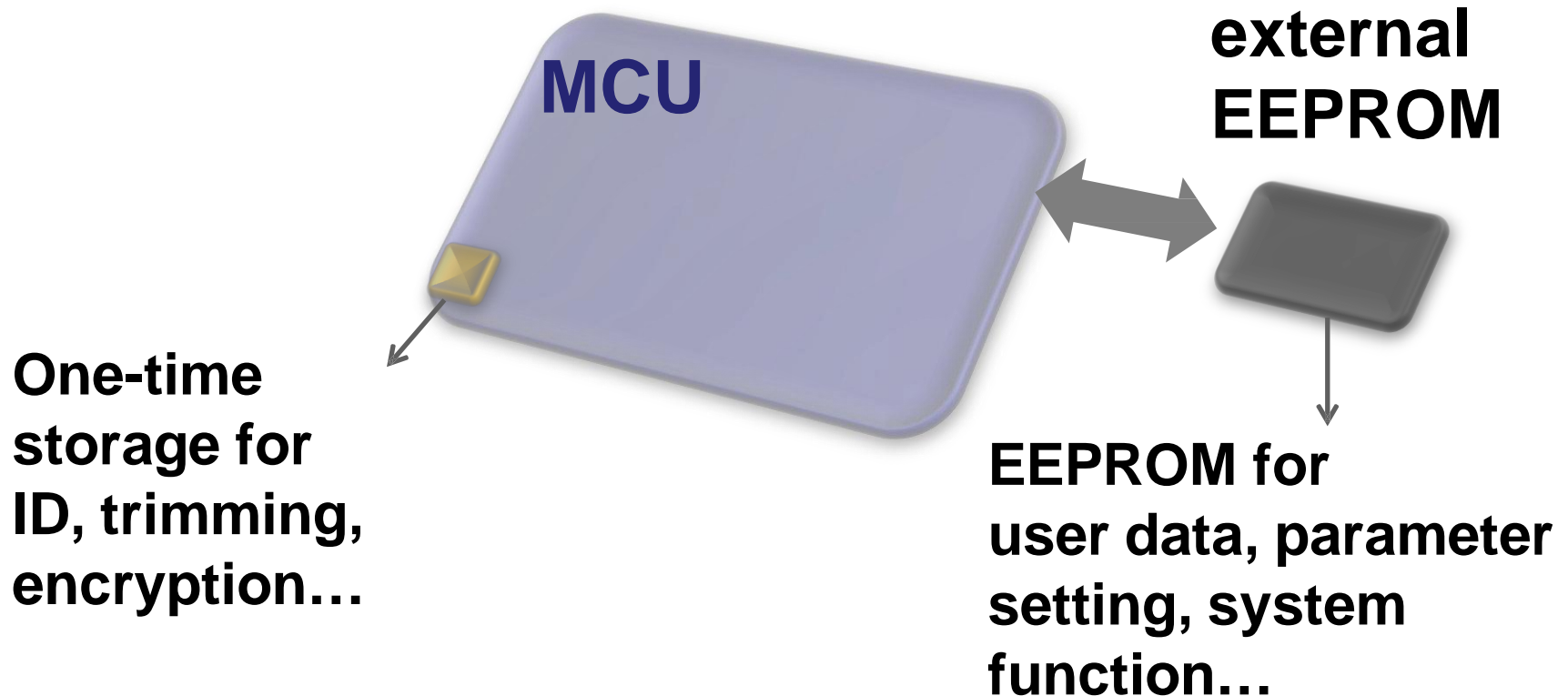**Logic Process + 10 Masks**

30% more cost reduction   *wafer cost & testing time*

MCU

eMemory inside
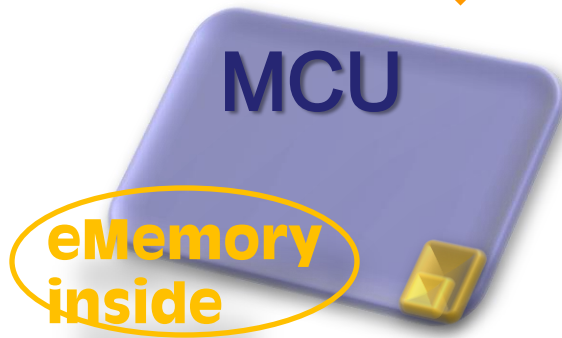
product design & manufacturing by Embedded Logic NVM (OTP/MTP) Logic Process

MCU Applications with EEPROM

MCU

external EEPROM

One-time storage for ID, trimming, encryption…

EEPROM for user data, parameter setting, system function…

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NeoBit + NeoEE

Hybrid NVM solution (NeoBit + NeoEE) with customized SPEC & optimized size

MCU

•One single IP by integration of NeoBit & NeoEE

•Help for system size reduction

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Wafer Demand by IC Type

IC Type	Equa to 8-inch wafer (K)
AP	4926
PMU	4508
Smart card controller	3667
Base Band controller	2429
CIS sensor	1975
LCD driver (int with TCON)	1892
Fingerprint	744
Gauge IC	670
Touch panel controller (C)	581
TV controller	579
Connectivity (Combo)	437
STB controller	330
Wifi controller	293
DC-DC/AC-DC	190
LED driver	141
BT controller	132
Light sensor	123
Accelerator sensor controller	114
TAG IC	100
ISP	98
Gyroscope sensor controller	90
MCU (8bits, pure 5V)	65
P-Gamma	40
MCU (8bits, LV/3.3V)	39
NB CAM controller	36
Pressure sensor controller	21
PC CAM controller	8
TCON (w/o driver)	3

2016 Q3 updated

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Outlook for 2017

- **In license revenues ：**

  › **Strong demand for building advanced process and MTP platform in worldwide foundry partners will increase technology license and design license revenues.**

- **In royalty revenues：**

  › **8" wafer royalty will grow further due to multiple fingerprint customers are ramping up production and more customers will start volume production later this year.**

  › **PMIC related royalty will increase due to new chips in fast charger 、wireless charger, and our largest US customer ramping up their new generation of PMIC in second half of 2017.**

  › **Automotive platforms have been successfully built and customers already start small volume production**

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Outlook for 2017

› For 12" wafer royalty, the volume production of TDDI, OLED, STB/ DTV, CIS and security have continuously increased.

› We had first 16nm tape-out in 2016. The 10nm IP have been successfully verified and 7nm test chip is expected to tape out in Feb. All these will increase our penetration rate in 12" fab.

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Key Growth Drivers

|	
Growth in application per mobile devices	• More chip applications per smartphone/tablet product.
Growth into more markets	• From consumer electronics and mobile devices to wearable devices. • Adding new NVM product lines further enable more product applications.
Growth in advanced technology	• Higher royalty per wafer is contributed from more advanced technology nodes.
Great IoT era	• Embedded Logic NVM will be a must.

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Q & A
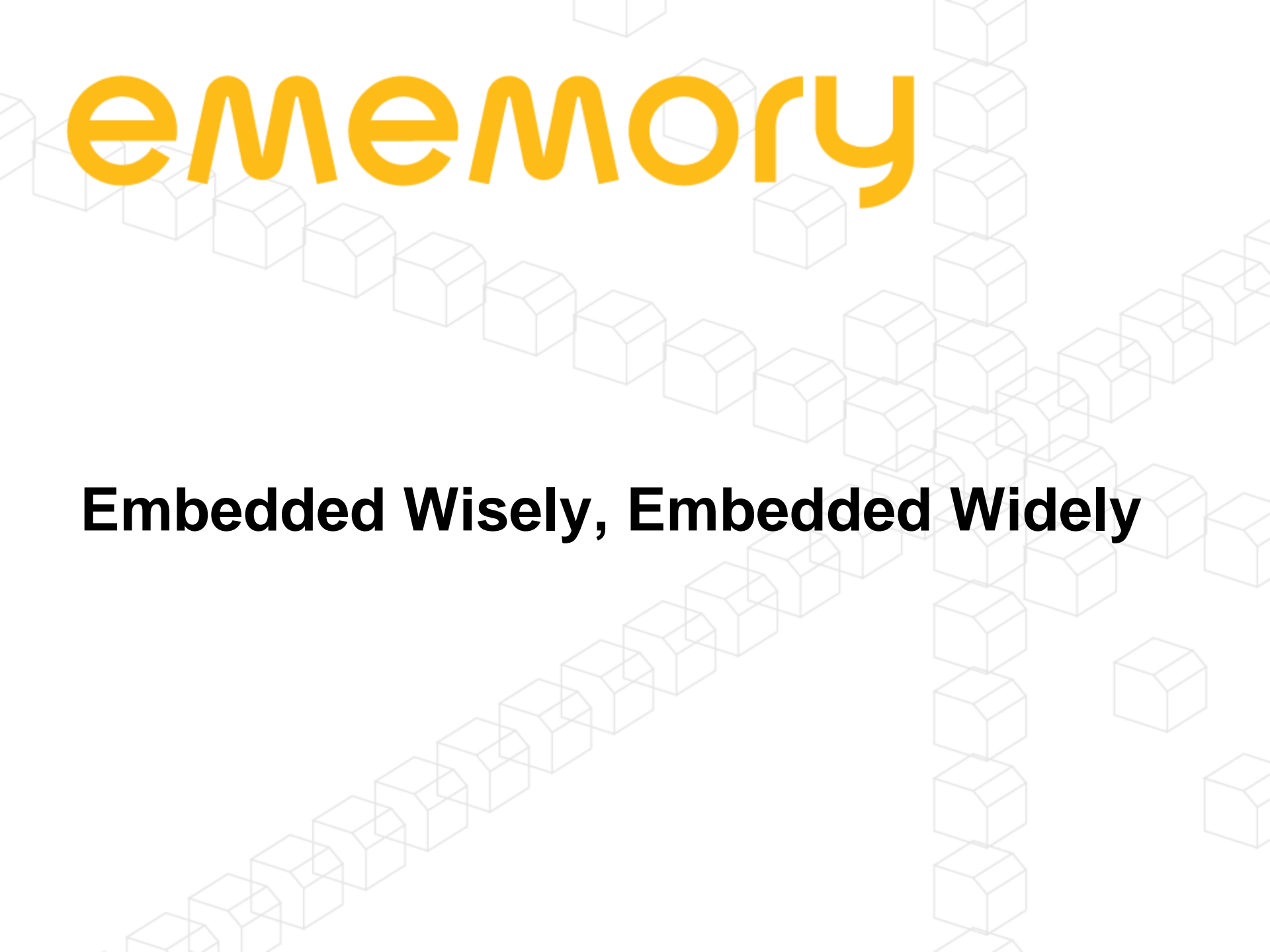
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